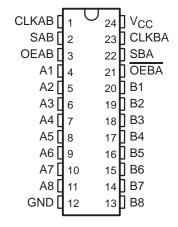
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Multiplexed Real-Time and Stored Data
- Inverting Data Paths
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

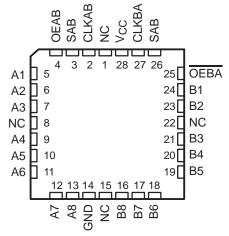
description

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. The select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT651 devices.

SN54ABT651 . . . JT PACKAGE SN74ABT651 . . . DB, DW, NT, OR PW PACKAGE (TOP VIEW)



SN54ABT651 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all the other data sources to the two sets of bus lines are at high impedance, each set remains at its last state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

description (continued)

The SN54ABT651 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT651 is characterized for operation from -40° C to 85° C.

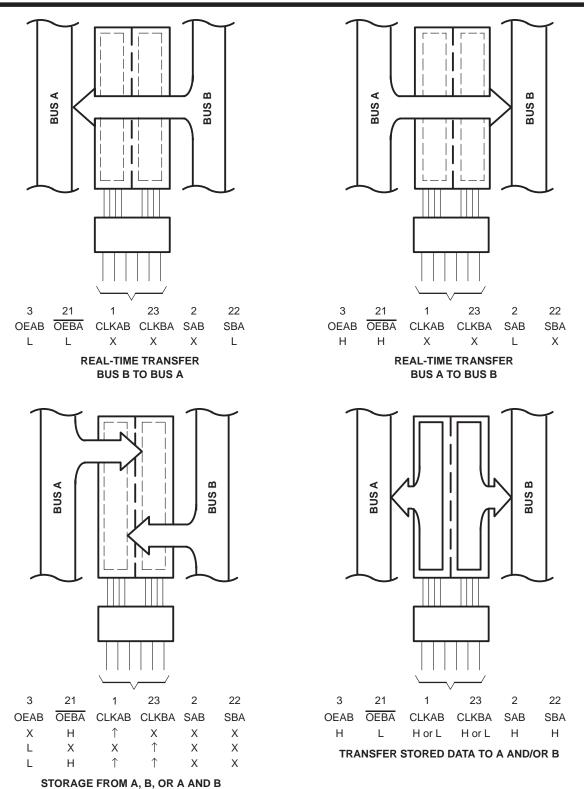
FUNCTION TABLE

		INPU ⁻	rs			DAT	A I/O	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	1	X	X	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Х	Input	Unspecified [†]	Store A, hold B
Н	Н	\uparrow	1	X‡	X	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified [†]	Input	Hold A, store B
L	L	\uparrow	1	Χ	X‡	Output	Input	Store B in both registers
L	L	Χ	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored \overline{B} data to A bus
Н	Н	Χ	Χ	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored \overline{A} data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



[‡] When select control is low, clocks can occur simultaneously if allowances are made for propagation delays from A to B (B to A) plus setup and hold times. When select control is high, clocks must be staggered to load both registers.



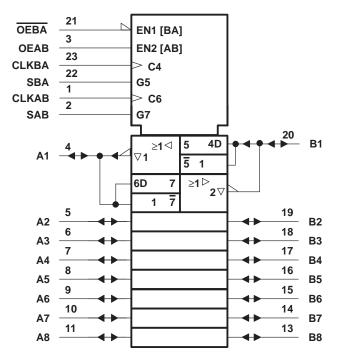
Pin numbers are for the DB, DW, JT, NT, and PW packages.

Figure 1. Bus-Management Functions



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

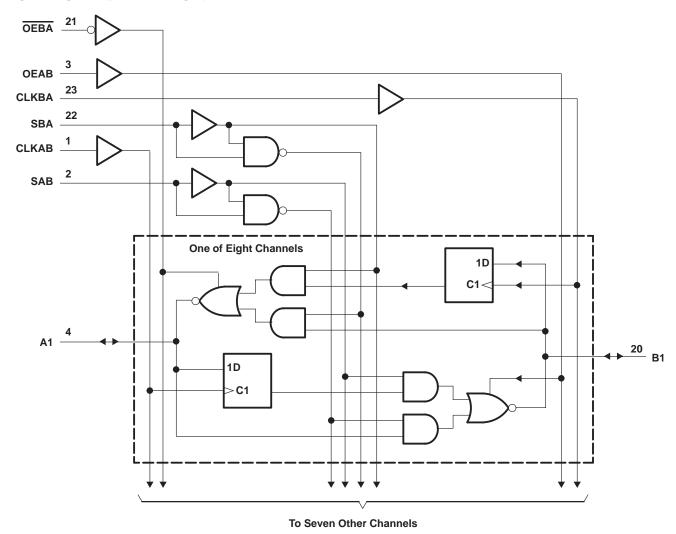
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and PW packages.



logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

SCBS083E - JANUARY 1991 - REVISED APRIL 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see N		
Voltage range applied to any output in the high	or power-off state, VO .	0.5 V to 5.5 V
Current into any output in the low state, Io: SNS	54ÅBT651	96 mA
SN	74ABT651	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	104°C/W
•••	DW package	81°C/W
	NT package	67°C/W
	PW package	120°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

		SN54ABT651		SN74A	BT651	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EN	2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ı	Input voltage	0 <	Vcc	0	VCC	V
IOH	High-level output current	(ر)	-24		-32	mA
lOL	Low-level output current	$g_{Q_{\ell}}$	48		64	mA
Δt/Δν	Input transition rise or fall rate) V	5		5	ns/V
TA	Operating free-air temperature	– 55	125	-40	85	°C

NOTE 3: All unused pins (control or I/O) of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Т	T _A = 25°C			BT651	SN74ABT651		UNIT		
PARAMETER	TEST CON	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII		
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
Va	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				v	
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
Vol	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL	VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55		
V _{hys}				100			4			mV	
Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		<u></u> ±1		±1	μΑ	
A or B ports	VCC = 3.5 V,	1 = 100 01 014D			±100		±100		±100	μΑ	
lozh [‡]	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ	
l _{OZL} ‡	V _{CC} = 5.5 V,	V _O = 0.5 V			-50	S	-50		-50	μΑ	
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	0			±100	μΑ	
ICEX	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	40	50		50	μА	
IO§	V _{CC} = 5.5 V,	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA	
	V _{CC} = 5.5 V,	Outputs high			250		250		250	μΑ	
VIK VOH VOL Vhys II Control inputs A or B ports IOZH [‡] IOZL [‡] IOFF ICEX IO§ ICC ΔICC¶	$I_{O} = 0$,	0, Outputs low			30		30		30	mA	
	$V_I = V_{CC}$ or GND	Outputs disabled			250		250		250	μΑ	
ΔICC¶	$V_{CC} = 5.5 \text{ V}$, One input Other inputs at V_{CC} of				1.5		1.5		1.5	mA	
C _i Control inputs	V _I = 2.5 V or 0.5 V			6						pF	
C _{io} A or B ports	V _O = 2.5 V or 0.5 V			7.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		V _{CC} = 5 V, T _A = 25°C		SN54ABT651		SN74ABT651		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		125		125		125	MHz
t _W	Pulse duration, CLK high or low	4		4	10,71	4		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3	71.	3		ns
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		0		ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

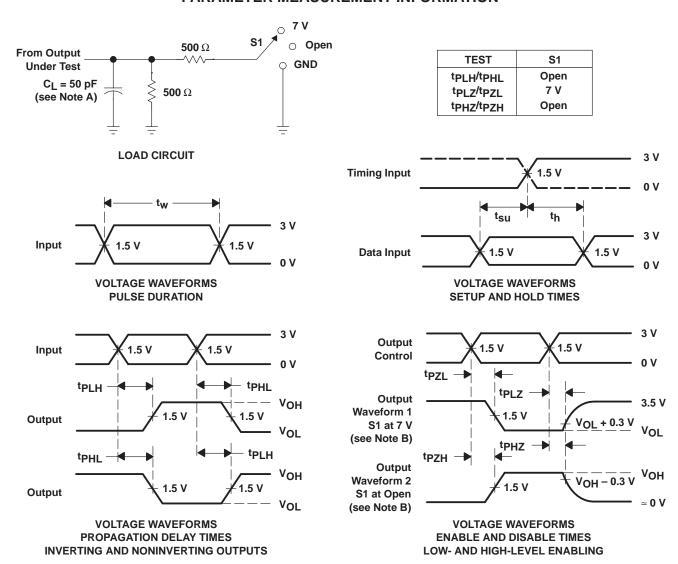
SCBS083E - JANUARY 1991 - REVISED APRIL 1998

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	I		V _{CC} = 5 V, T _A = 25°C		SN54ABT651		SN74ABT651		UNIT
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			125			125		125		MHz
^t PLH	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.9	2.2	5.6	ns
^t PHL	CLNBA OF CLNAB	AOIB	1.7	4	5.1	1.7	5.9	1.7	5.6	115
^t PLH	A or B	B or A	1.5	4	5.1	1.5	6.4	1.5	6.2	ns
t _{PHL}		BOIA	1.5	3.3	4.6	1.5	5.6	1.5	5.4	115
t _{PLH}	SAB or SBA†	A or B	1.5	4	5.1	1.5	6.8	1.5	6.5	ns
^t PHL		AOIB	1.5	3.6	4.9	1.5	6.2	1.5	5.9	115
^t PZH	OEBA	А	1.3	3.6	4.6	1.3	5.9	1.3	5.8	ns
t _{PZL}	OEBA	A	2.5	5.7	6.8	2.5	8.9	2.5	8.5	115
^t PHZ	OEDA	А	1.5	3.2	4.5	91.5	6.2	1.5	5	ns
^t PLZ	OEBA	٨	1.5	3	3.8	1.5	4.3	1.5	4.1	115
^t PZH	OEAB	В	1.8	4.3	6.1	1.8	6.7	1.8	6.5	ns
tPZL		ט	2.9	5.5	6.5	2.9	7.6	2.9	7.4	115
^t PHZ	OEAB	В	1.5	3.3	4.5	1.5	6.5	1.5	5.5	ns
^t PLZ	OLAB	ь	1.5	3.4	4.4	1.5	5.2	1.5	5.1	110

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated